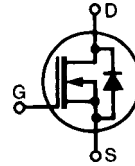


# High Voltage MOSFET IXTP 01N100D

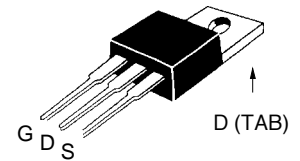
N-Channel, Depletion Mode

$V_{DSS} = 1000 \text{ V}$   
 $I_{D25} = 100 \text{ mA}$   
 $R_{DS(on)} = 110 \text{ } \Omega$



Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	1000	V
$V_{DGR}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}; R_{GS} = 1 \text{ M}\Omega$	1000	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_C = 25^\circ\text{C}; T_J = 25^\circ\text{C to } 150^\circ\text{C}$	100	mA
$I_{DM}$	$T_C = 25^\circ\text{C}$ , pulse width limited by $T_J$	400	mA
$P_D$	$T_C = 25^\circ\text{C}$	25	W
	$T_A = 25^\circ\text{C}$	1.1	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	1.6 mm (0.063 in.) from case for 10 s	300	$^\circ\text{C}$
<b>Weight</b>		1	g

TO-220AB (IXTP)



## Features

- Normally ON mode
- Low  $R_{DS(on)}$  HDMOS™ process
- Rugged polysilicon gate cell structure
- Fast switching speed

## Applications

- Level shifting
- Triggers
- Solid state relays
- Current regulators

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{DSS}$	$V_{GS} = -10 \text{ V}, I_D = 25 \text{ } \mu\text{A}$	1000		V
$V_{GS(off)}$	$V_{DS} = 25 \text{ V}, I_D = 25 \text{ } \mu\text{A}$	-2.5		V
$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}_{DC}, V_{DS} = 0$			$\pm 100 \text{ nA}$
$I_{DSS(off)}$	$V_{DS} = V_{DSS}, V_{GS} = -10 \text{ V}$ $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$			10 $\mu\text{A}$
				250 $\mu\text{A}$
$R_{DS(on)}$	$V_{GS} = 0 \text{ V}, I_D = 50 \text{ mA}$ Note 1	90	110	$\Omega$
$I_{D(on)}$	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}$ Note 1	250		mA

Symbol	Test Conditions		Characteristic Values		
			min.	typ.	max.
$g_{fs}$	$V_{DS} = 50 V; I_D = I_{D25}$	Note 1	100	150	mS
$C_{iss}$	$V_{GS} = -10 V, V_{DS} = 25 V, f = 1 MHz$			120	pF
$C_{oss}$			15	pF	
$C_{rss}$			3	pF	
$t_{d(on)}$	$V_{gs} = 0 V, \text{ to } -10 V, I_D = 50 mA$			8	ns
$t_r$			6	ns	
$t_{d(off)}$			30	ns	
$t_f$			51	ns	
$R_{thJC}$				5	K/W

Source-Drain Diode		Characteristic Values		
		$(T_J = 25^\circ C, \text{ unless otherwise specified})$		
Symbol	Test Conditions	min.	typ.	max.
$V_{SD}$	$V_{GS} = -10 V, I_F = I_{D25}$	Note 1	1.0	1.5 V
$t_{rr}$	$I_F = 0.75 A, -di/dt = 10 A/\mu s,$ $V_{DS} = 25 V, V_{GS} = -10V$			1.5 $\mu s$

Note 1: Pulse test,  $t \leq 300 \mu s$ , duty cycle  $d \leq 2 \%$

**TO-220 AD Dimensions**

Pins: 1 - Gate, 2 - Drain, 3 - Source, 4 - Drain Bottom Side

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETS and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715  
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025